

ABSTRACT OF THE DISCLOSURE

A semiconductor device is disclosed, which comprises a package board in which pads are formed on the upper side of a wiring board, a semiconductor chip in which first bumps are formed on the device-forming surface of the semiconductor chip, second bumps are formed on the back surface of the semiconductor chip, and the semiconductor chip is flipchip-connected to the package board, a capacitor-mounted board in which capacitors are mounted on the upper surface of the capacitor-mounted board, pads are formed on the back surface of the capacitor-mounted board, and the capacitor-mounted board is flipchip-connected to the semiconductor chip, an adhesive resin filled between the semiconductor chip and the package substrate and between the semiconductor chip and the capacitor-mounting board, resin package formed on the package substrate, and a ball grid array comprising a plurality of external terminal balls formed on the back surface of the package substrate.